IN THE CLAIMS

1 (Previously Presented). A method comprising:

temporarily flattening a sheet by applying a flattening force to the center of said sheet;

applying row and column electrodes to said sheet while said sheet is held in a flattened configuration; and

securing said sheet to a second sheet that is solid while continuing to hold the center of said sheet in a flattened configuration.

2 (Original). The method of claim 1 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

Claim 3 (Canceled).

4 (Previously Presented). The method of claim 1 wherein processing said sheet includes applying a light emitting material to said sheet.

5 (Original). The method of claim 4 wherein applying a light emitting material to said sheet includes applying an organic light emitting material between said row and column electrodes.

6 (Original). The method of claim 1 further including processing said second sheet in a flattened configuration.

7 (Original). The method of claim 6 including processing said second sheet in a chuck.

8 (Original). The method of claim 7 including processing both said first and second sheets in chucks and combining said sheets using said chucks.

9 (Original). The method of claim 1 including securing said first and second sheets to an integrator plate.

10 (Original). The method of claim 9 including surface mounting said first and second sheets.

11 (Original). The method of claim 8 including surface mounting said first and second sheets in said chucks.

12 (Previously Presented). A method comprising:

receiving a warped sheet;

temporarily flattening said sheet for processing by applying a force to the center of said sheet;

processing said center flattened, warped sheet by applying electrodes to said sheet; and

securing said center flattened, warped sheet to a planar surface.

13 (Original). The method of claim 12 including securing said flattened sheet to a second sheet while continuing to hold said flattened sheet in a flattened configuration.

14 (Original). The method of claim 12 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

15 (Original). The method of claim 12 including securing said flattened sheet to a rigid, planar integrating plate.

16 (Previously Presented). A method comprising:

temporarily flattening a ceramic sheet by applying a force to the center of said sheet;

processing a glass panel to define row and column electrodes thereon while continuing to hold the center of said sheet in a flattened configuration; and

securing said sheet to said glass panel while continuing to hold the center of said sheet in a flattened configuration.

17 (Original). The method of claim 16 including securing said sheet and said panel to an integrating plate.

18 (Original). The method of claim 16 wherein temporarily flattening the ceramic sheet by placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

19 (Original). The method of claim 16 wherein processing said panel further includes applying an organic light emitting material between said row and column electrodes.

20 (Original). The method of claim 16 further including processing both said sheet and said panel in chucks and combining said sheet and said panel using said chucks.